

Research Plan:  
(rolling)

Documentation setup GitLab and Hackaday  
Approximate examples for interest generation in multiple segments.  
Concept framework and brainstorming.  
Joint (connectors) research and integration plan  
Technical feasibility decisions (normal to bounding box vs other method)  
Initial contacts and feedback channels  
Environmental impact study  
Figure out component size > material decisions  
Scale units for testing  
Material properties and optimization (will impact scale and appearance)  
Optimization for production and best practices.  
Geometric approximations for multiple materials with supplied tables  
Rule set construction and discovery.  
New user evaluations and writeup  
Outreach for further development  
Use case modifications and adaptations  
Documentation verification  
Rolling certification for classes of artifacts through Open Source Hardware Association  
Feedback loops and streamlining aesthetic considerations  
Secondary rollout and feedback loops.  
Education and outreach  
Verification of environmental impact and real world use cases.  
Backwards propagation (computer integration and component libraries for best fit use.)  
Full optimization and toolkit integration.  
Individual outreach.  
Applied research and industrial outreach.  
Multi scale pilot programs and compatibility verification (bridge components between full and half scale ex.)

Price of admission: Experimental design language tool, easy to communicate designs, structurally sound, scalable in utilization. (modules are not single purpose.)  
Outreach methods: Open source (discoverable), individual outreach, company integration outreach.  
Documentation: Open Source Hardware Guidelines and Best Practices  
Overall model: Tool over individual product.